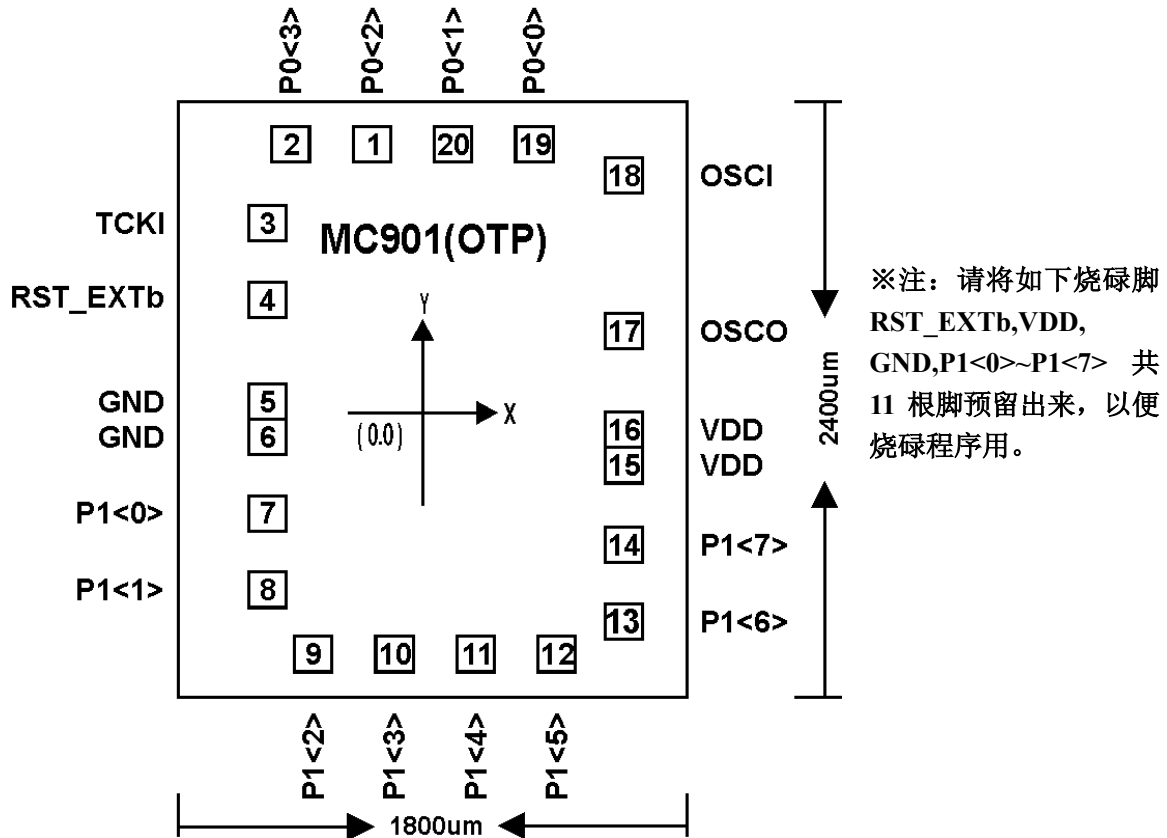


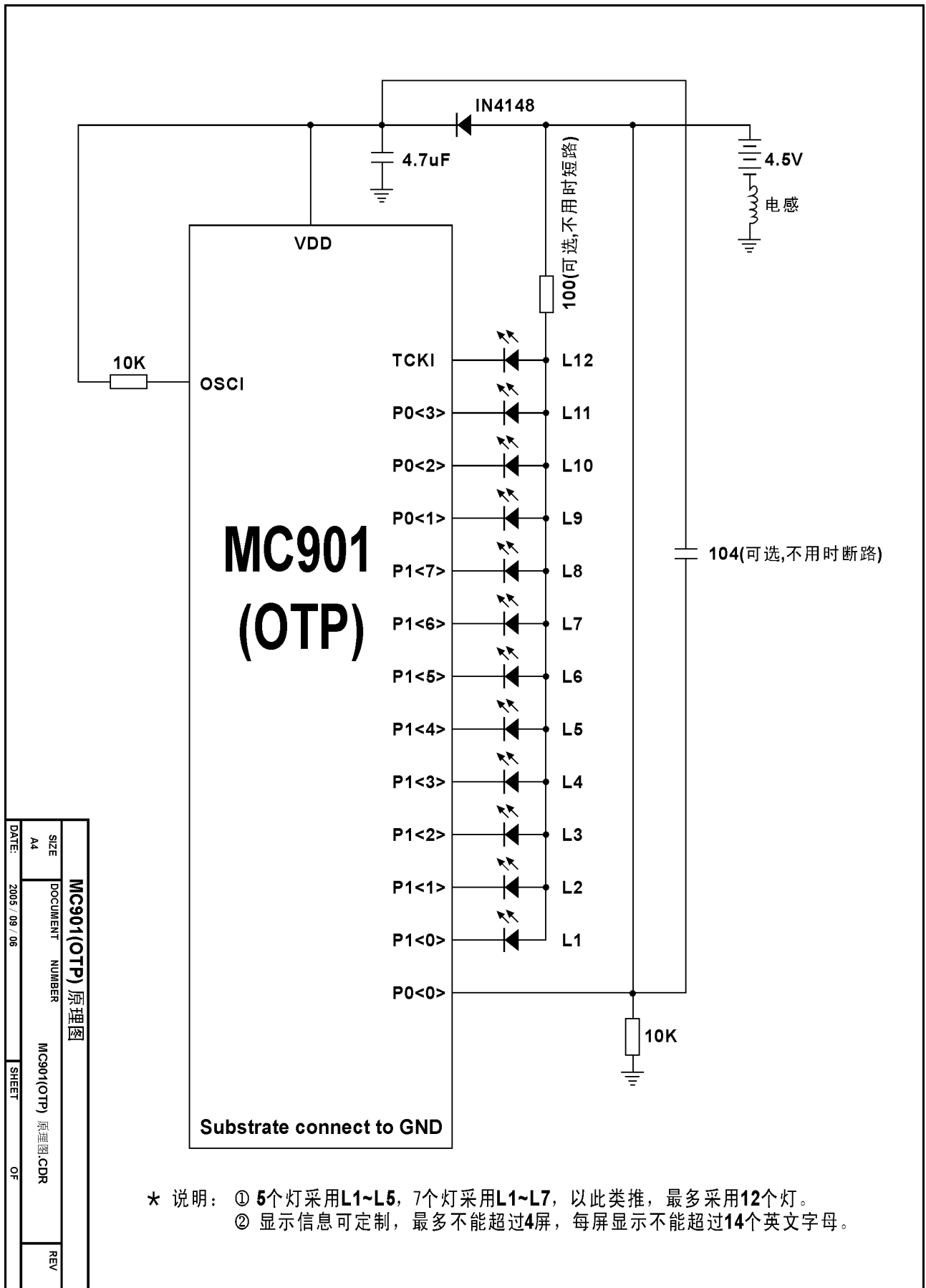
MC901 规格书

Bonding Diagram



Substrate connect to GND

Pad No.	Designation	X(um)	Y(um)	Pad No.	Designation	X(um)	Y(um)
1	P0<2>	483.33	1544.89	11	P1<4>	795.08	189.18
2	P0<3>	257.37	1544.89	12	P1<5>	1021.04	189.18
3	TCKI	189.18	1360.96	13	P1<6>	1236.07	270.37
4	RST_EXTB	189.18	1183.56	14	P1<7>	1236.07	496.33
5	GND	189.19	778.64	15	VDD	1236.07	732.63
6	GND	189.19	841.19	16	VDD	1236.07	795.18
7	P1<0>	189.18	602.71	17	OSCO	1236.07	1044.43
8	P1<1>	189.18	376.75	18	OSCI	1236.07	1477.42
9	P1<2>	328.50	189.18	19	P0<0>	958.10	1544.89
10	P1<3>	554.46	189.18	20	P0<1>	732.14	1544.89



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